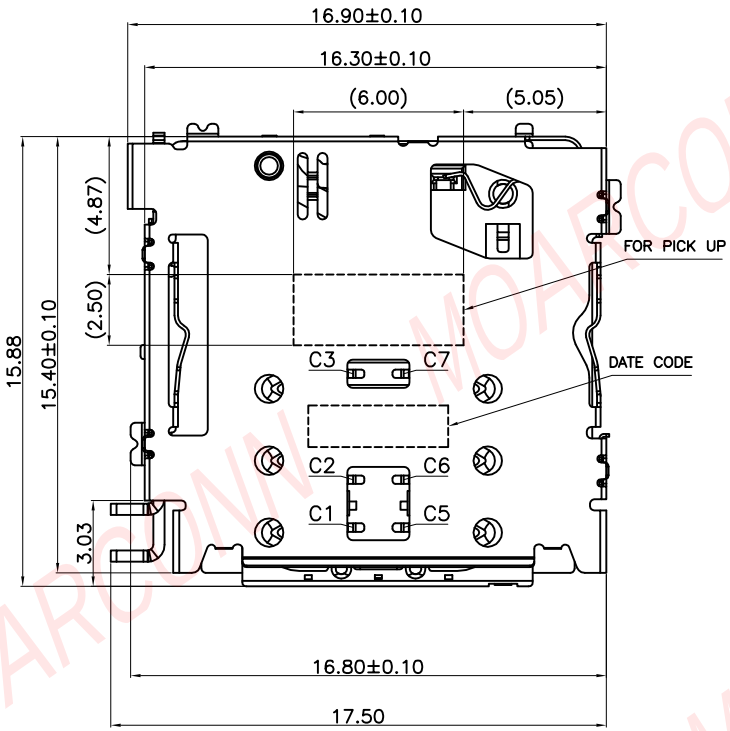
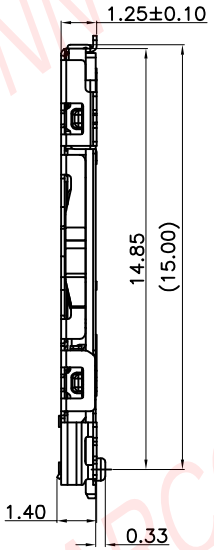
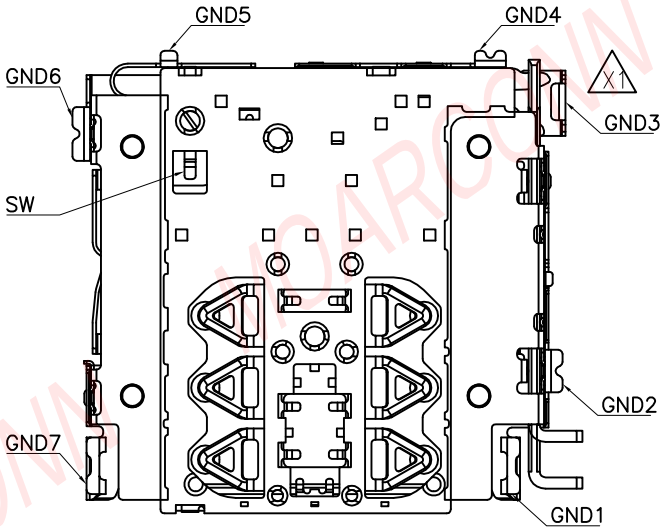
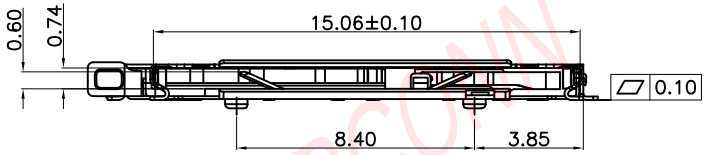
All materials, plating and process meet HF requirements.









REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X1	----	Modify the soldering pins	Shilikai	2025.11.07
X0	----	NEW RELEASE	Aaron	2025.01.06

MOARCONN®
More Connections Smart Future

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

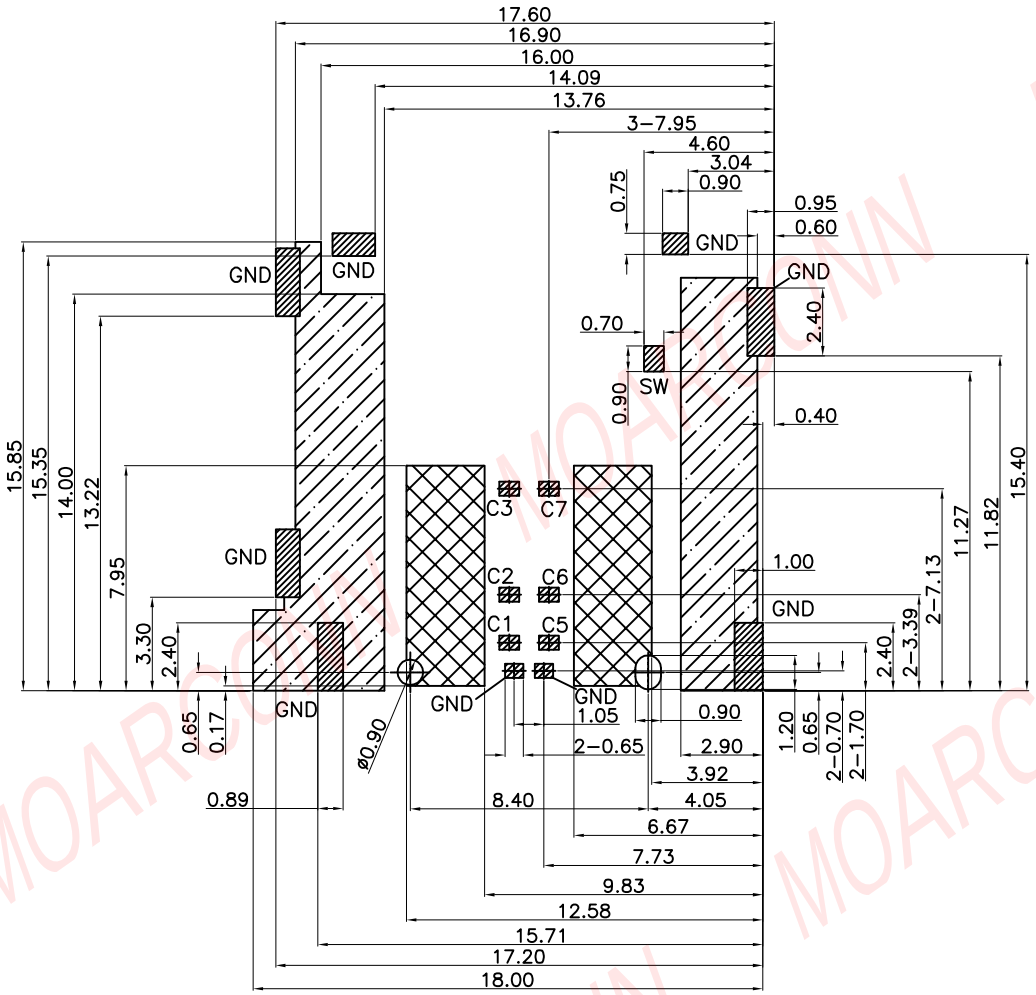
DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.25
X.XXX: ±	0.10
ANGULAR: ±	2°

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

PRODUCT NAME : NANO SIM H1.25 Pin Eject	DRAWING: Shilikai	DATE: 2025.11.07	
PRODUCT NO. : NS125-T1131-30	CHECK: /	DATE: /	
DRAWING NO. : D-NS125-T1131-30	APPROVED:	DATE:	
	SCALE: 1:1	DWG ID: C D	REV.: X1	PAGE: 1 OF 2

MOARCONN

All materials, plating and process meet HF requirements.



RECOMMEND P.C.B LAYOUT(TOP VIEW)
(Tolerances Unless Otherwise Spec. ±0.05)

THIS AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES

SIM SOLDER AREA

OPEN WIRE RESTRICTED AREA
(POSSIBLY TOUCH OF COMPONENTS ON PCB)

NOTE:

1. Material:
   - 1-1 Housing:High Temperature Thermoplastic,(LCP 抽粒475)Color Black UL 94V-0
   - 1-2 Contact: Phosphor Bronze(C5210R-SH,T=0.10±0.01mm)
   - 1-3 Cover: SUS304-H T=0.12±0.03mm
2. Plating:
   - 2-1 Contact terminal:
     Contact area: Gold 1u" Min.Solder area: Gold Flash .
     Underplating: Ni overall 50U" Min.
   - 2-2 Cover:
     Underplating: Ni overall 30U" Min. Solder area: Gold Flash .
3. Specification:
   - 3-1.Current Rating :0.3A PER PIN
   - 3-2.Current Voltage :10V AC
   - 3-3.Contact Resistance: 50 mOhms max
   - 3-4.Insulation Resistance:1000 MOhms min./500VDC
   - 3-5.Dielectric Withstanding Voltage:500 V AC/1minute
   - 3-6.Operating Temperature:-25°C to+85°C
   - 3-7.Tray Insertion force: 40N Max
   - 3-8.Tray Extraction force: 1~8N
   - 3-9.Tray Ejector Pin force: 15N Max
   - 3-10.Duradility:2000 Cycles Min
4. Product Compliant to HalogenFree+ RoHS2 Directive 2002/95/EC and ELV 2000/53/EC
5. Recommending A Metal More Than 0.15mm Thick.
   Please Confirm Solderadility, If Use A Metal Mask Less Than 0.15mm Thick.

NANO SIM-PIN	
C1	Vcc
C2	RST
C3	CLK
N/A	Reserved
C5	GND
C6	Vpp
C7	I/O
N/A	Reserved

COMPOSITION OF DETECTION

NORMAL:

SW o-o-o-o GND

TRAY INSERT:

SW o-o-/ o-o GND

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
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X0	----	NEW RELEASE	Faji	2025.01.06

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			PAGE: 2 OF 2

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